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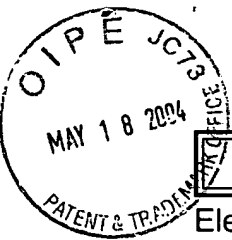
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 61211
Application ID: 10774893
Title of Invention: LEADFRAME FOR SEMICONDUCTOR PACKAGE
First Named Inventor: HYUNG LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-02-09
Effective Receipt Date: 2004-05-18
Submission Type: Information Disclosure Statement
Filing Type:
Confirmation number: 8761
Attorney Docket Number: AMKOR006C




Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US
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Electronic Version v1.1
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Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
<p>Application Number: 10/774893 </p> <p>Date: 2004-02-09</p> <p>First Named Applicant: HYUNG JU LEE</p> <p>Confirmation Number: 8761</p> <p>Attorney Docket Number: AMKOR006C</p>										
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Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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	us-ids.dtd									
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Comments										



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Electronic Version v18
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Application Number: 10/774893							
Confirmation Number: 8761							
First Named Applicant: HYUNG LEE							
Attorney Docket Number: AMKOR006C							
Art Unit: 2811							
Search string: (5608265 or 5608267 or 5625222 or 5633528 or 5639990 or 5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5724233 or 5723899 or 5726493 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or 5877043 or 5886397),pn.							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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Signature

Examiner Name	Date